Press Release

FOR IMMEDIATE RELEASE

KELINGTON SECURES RECORD-HIGH USD452 MILLION LOA FOR TURN-KEY TOTAL FACILITY TOOL HOOKUP SERVICES (ADVANCED ENGINEERING) FOR SEMICONDUCTOR WAFER FAB IN INDIA

Kuala Lumpur, 14 September 2026 – Integrated engineering solutions provider, Kelington Group Berhad ("**Kelington**" or the "**Group**") (stock code:0151) through its wholly-owned subsidiary Kelington Engineering (S) Pte. Ltd. ("**KESG**"), has accepted a Letter of Award ("**LOA**") with a provisional contract price of USD 452 million (approximately RM1.83 billion) for the turn-key total facility tool hookup services for a semiconductor wafer fabrication facility in Gujarat, India.

Under the LOA, Kelington will act as the main contractor and undertake the overall design, installation, connection, testing and handover of manufacturing, laboratory and support tools, together with related tool-specific support systems for Module 1 and Module 2 of the facility. The works are expected to be completed over a period of 30 months, with completion targeted by Feb 2029.

The provisional contract price comprises USD249.9 million (approximately RM1.01 billion) for Module 1 and USD 202.0 million (approximately RM817.2 million) for Module 2, covering up to 886 tools across both modules. The final contract value will be determined based on the actual quantities of tools and services executed.

Mr. Lim Seng Chuan (林成全), Chief Executive Officer of Kelington Group Berhad said, "Winning this landmark USD 452 million semiconductor project is a defining moment for the Group. It is not only the largest project we have ever secured since our establishment, but also a strong validation of our capabilities, technology and execution track record. It marks another important step in elevating our contracting and management capabilities to become a main contractor in semiconductor turn-key total facility tool hookup services. This project provides us with an important platform to deepen our presence in the semiconductor industry and create opportunities for further growth."

"This latest contract builds on an earlier award secured from the same client for a different scope of work. The repeat award reflects the client's continued confidence in our capabilities and execution track record especially in Technology and Process Solutions (Advanced Engineering). Turn-key Total Facility Tool hookup is a critical part of bringing semiconductor manufacturing equipment into operation, requiring close coordination across multiple engineering disciplines and stringent execution standards," he added.

"India is making significant investments to build its domestic semiconductor manufacturing capabilities, and we believe Kelington is well positioned to participate in this development. The scale of this award further strengthens our presence in the market and provides us with a solid foundation to pursue further opportunities as India's semiconductor ecosystem continues to expand. Together with our inclusion in the MSCI Malaysia Small Cap Index and our AAA rating by MSCI ESG Ratings, this award reflects the Group's steady progress in building a stronger global profile through our expanding international footprint and growing visibility among global investors. In addition, we remain focused on executing the projects successfully, delivering value to our customer and shareholders, and building the capabilities required to compete for larger and more sophisticated projects globally," Mr Lim concluded.

For the six months ended 30 June 2026, the Group secured RM1.23 billion in new contracts. Including subsequent contract wins of RM538 million and the RM1.83 billion hookup contract, total year-to date wins stood at RM3.59 billion. With this, the Group maintains robust earnings visibility in the coming years.

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ABOUT KELINGTON GROUP BERHAD ("Kelington" or the "Group")

Kelington Group Berhad, listed on the Main Market of Bursa Malaysia Securities Berhad, is an integrated engineering solutions provider with a core focus on advanced engineering and process systems, particularly for the semiconductor and electronics industries. The Group delivers end-to-end engineering solutions ranging from system design to fabrication and installation of equipment as well as building manufacturing facilities. Via Ace Gases Sdn Bhd, its wholly owned subsidiary, the Group is also a key player in the industrial gas sector, supplying a comprehensive range of industrial and electronic specialty gases. Its engineering services extend to gas plant design, on-site gas generation, and customised gas delivery systems, serving diverse industry applications.

For more information, please log on to http://kelington-group.com

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Released on behalf of Kelington Group Berhad by Capital Front Investor Relations.

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